

# semiconductor packaging news

EV Group Brings High-Speed High-Precision Metrology to 3D Heterogeneous Integration – November 18, 2021

## semiconductor packaging news

We search for industry news, so you don't need to.

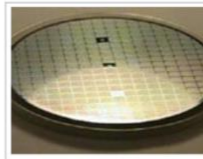
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November 18, 2021

### Revenue Growth to Skyrocket Among Top 25

IC Insights' November Update to The McClean Report was recently released. Included in the update were several year-end forecasts for semiconductor sales, capex, and a ranking of top sales leaders. Among the data was IC Insights' projected ranking of the top 25 semiconductor suppliers ranked by sales growth rate. The semiconductor market is forecast to increase 23% this year ...

**IC Insights**



### Have you seen wafer wands without hoses?

Our PORTA-VAC and PORTA-WAND wafer wands eliminate vacuum lines. Rechargeable wands and alkaline battery powered tools are available.

**Virtual Industries, Inc.**



### 2x Faster, 1/2 the Capital Cost, 1/2 the Footprint

Looking for revolutionary productivity for your advanced technologies? YES Plasma Resist/Descum Systems have high throughput & strip rate.

**Yield Engineering Systems, Inc.**



### UK Widens Probe of Nvidia-Arm Deal

The U.K. government has launched a 24-week, follow-up investigation into Nvidia's proposed acquisition of IP vendor Arm, citing and competition and national security ...

**EE Times**

### Die Attach for 5G Designs

How capable is your die attach material for 5G devices? Increasingly integrated designs, more die per package and higher reliability demands are pushing conventional ...

**Technical Paper**

### This new startup has built a record-breaking 256-qubit quantum computer

At long last, physicists from Harvard and MIT have found the killer application for quantum computing: a Mario Bros. GIF made from qubits. The qubits (quantum bits) can ...

**MIT Technology Review**

### Technical Papers

- [Preparing TEM Specimens and Atom Probe Tips by Laser Machining](#)
- [High Thermal Non-Conductive Die Attach](#)
- [High-Resolution Roughness Metrology for the Wafer Fab](#)
- [Efficient Manufacture of IR Sensors](#)
- [Qualifying the ExposedPad TQFP for AEC-Q006 Grade 0](#)
- [How to Wire Pull?](#)
- [Monolithic Magnetic Sensors Manufactured by Selective Laser Annealing](#)

### Merry Christmas and Happy New Year

To our friends and readers around the world, may you find peace and happiness during the holiday season. We wish you and your families a happy holiday. We'll be back after New Year's.

**Circuitnet Media LLC**



Today's Sponsor



### Test Your Knowledge

Name the chemical elements in The Periodic Table beginning with the letter "S".

See answer below.

### Achieving low voiding for power devices

For power device applications where low void concentration & reduced costs are important, learn how the solder paste solution, with different pressures results in higher yields.

**SST Vacuum Reflow Systems**



### Press Releases

#### [EV Group Brings High-Speed High-Precision Metrology to 3D Heterogeneous Integration](#)

EV Group unveiled the EVG540 NT2 automated metrology system, which provides overlay and critical dimension (CD) measurements for wafer-to-wafer (W2W), die-to-wafer ...

**EV Group**

#### [ITW EAE to Showcase New Printer and Dispenser Developments at Semicon Taiwan](#)

ITW EAE will be showcasing its latest printer and dispenser developments at Semicon Taiwan, December 28-30 at the Nangang Exhibition Center in Taipei. Applications Experts ...

**ITW EAE**

#### [Park Systems Announces Combined AFM and WLI Tool](#)

Park Systems presents Park NX-Hybrid WLI, the first fully integrated system that combines Atomic

### Ormet® via-fill pastes enable high-yield single-lamination PCBs

Ormet® delivers high reliability any-where and any-layer vias for high density interconnects in complex printed circuit boards.

**EMD Electronics**



### FPGA makers complicit in sustainability of defense grade parts

A small number of civilian in supply chain bet on a single source subcontractor who provides 90% of FPGA solder columns. High stakes gamble.

**TopLine**



### Texas Instruments selects Sherman for new plant site

For months now, Sherman has been in a tight race against Singapore for a new Texas Instruments manufacturing plant. After a long wait, TI finally announced their decision. ...

**KXII**

### Nvidia data center sales grew 55% on demand for artificial intelligence chips

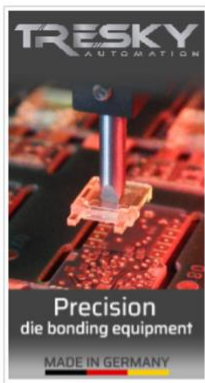
Nvidia stock rose more than 5% in extended trading after it reported earnings for its third fiscal quarter that beat expectations for both earnings and sales. The ...

**CNBC**

### Visions of a U.S. Computer Chip Boom Have Cities Hustling

The shortage of computer chips has zapped energy from the global economy, punishing industries as varied as automakers and medical device manufacturers and ...

**The New York Times**



### Blog Review: Nov. 17

In a podcast, Arm's Geof Wheelwright and Hilary Tam chat about the importance of efforts to decarbonize compute and how low-power compute can help ensure that the ...

**Semiconductor Engineering**

### IBM CEO says inflation fears could trigger 'some chaos'

IBM CEO Arvind Krishna has told CNBC he's "always worried" about inflation and warned of possible disruption ahead. "With all of the liquidity, and the fears of inflation raising ...

**CNBC**

### Qualcomm, BMW team up for automated driving

Qualcomm has announced a collaboration to bring the latest advancements in driver assistance technologies and products of its Snapdragon Ride Platform to BMW Group's ...

**Digitimes**

### Take your electronics assembly further, faster

Everything you need for plasma surface treatment, selective soldering, fluid dispensing and conformal coating. Learn more.

**Nordson ELECTRONICS SOLUTIONS**



### Descum processing for WLP

High volume manufacturing solution for wafer bumping packaging and advanced packaging. Removing of residues after development, processing and resist strip.

**Trymax Semiconductor Equipment**



Force Microscopy (AFM) with White Light Interferometer (WLI) profilometry ...

**Park Systems**

### BGA Component Rework Simplified

When you're confronted with tough BGA rework, who do you turn to? Discover the #1 resource used by military contractors. We have solutions for all your BGA rework and repair needs.

**Circuit Technology Center**



### Quote of the Day

"Nothing exists except atoms and empty space; everything else is opinion."

**Democritus**

### BGA Component Rework Simplified

When you're confronted with tough BGA rework, who do you turn to? Discover the #1 resource used by military contractors. We have solutions for all your BGA rework and repair needs.

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### Plasma Clean, Etch and RIE in One Machine

The PE-100 convertible allows you to perform plasma cleaning, isotropic etching and reactive ion etching (RIE) in the same system!

**Plasma Etch**



### What Year Was It?

#### Terry Waite Released

Shiite Muslim kidnappers in Lebanon free Anglican Church envoy Terry Waite after more than four years of captivity.



**The day was Nov 18. What year was it?**

### NanoResolution MRS™ Sensor

Fast, Superior Inspection Performance. Increase throughput with the NanoResolution MRS™ Sensor that is 2-3x faster, delivering greater than 25 wafers (300mm) per hour. Learn more.

**CyberOptics Corporation**



### Your Chips are Precious Cargo

Gel-Pak's LCS2™ Waffle Pack Lid eliminates component out-of-pocket defects resulting from die migration so your valuable devices arrive defect-free & ready for assembly.

**Gel-Pak, a Division of Delphon**



### NASA's Laser Demonstrations Extend to Deep Space

NASA plans to launch a pair of laser communications missions over the next nine months that would demonstrate high-bandwidth optical relays capable of someday transmitting ...  
EE Times

#1 bond testers

Put it to the test!

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EVG

ACCELERATING HETEROGENEOUS INTEGRATION

World-class wafer-to-wafer and die-to-wafer hybrid bonding solutions for 3D/HI production success

LEARN MORE

### Cartoon of the Day



"It says on your resume that you were created in God's image. Very impressive."

Copyright © Randy Glasbergen

### Amkor's Wafer Level Packaging Solutions

Amkor offers a broad array of Wafer Level Packaging capabilities and processes for packaging schemes from fan-out to chip scale to 3D to SiP.

**Amkor Technology, Inc.**



### Calendar

- **Nov 18, 2021: SEMICON Europa 2021 | In-person Event**
- **Dec 6, 2021: Overview of Semiconductor Manufacturing ( During SEMI West week)**
- **Dec 7, 2021: SEMICON West 2021 | Hybrid Event**
- **Dec 11, 2021: IEEE International Electron Devices Meeting**

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**Trymax Semiconductor Equipment**



### Test Your Knowledge Answer

Name the chemical elements in The Periodic Table beginning with the letter "S".

Answer: Silver (Ag), sodium (Na), sulphur (S), silicon (Si), selenium (Se), scandium (Sc), samarium (Sm), strontium (Sr)

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